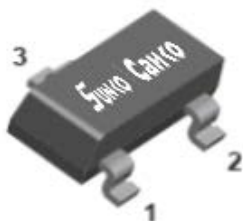
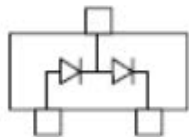


MMBD3004S

Dual Switching Diode



SOT-23

Features

- Moisture sensitivity level 1
- Reverse voltage: 300V
- Average forward current : 225mA

Application

- Signal switching
- High frequency rectifier

Mechanical data

- **Package:** SOT-23
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102

■ Maximum Ratings (T_a=25°C Unless otherwise specified)

Parameter	Symbol	Unit	Value
Device marking code			4P
Repetitive peak reverse voltage	V _{RRM}	V	350
Forward current	I _F	mA	225
Non-repetitive Surge peak forward current @ t=1us	I _{FSM}	A	4
Non-repetitive Surge peak forward current @ t=1s			1
Power dissipation	P _D	mW	350
Junction temperature	T _J	°C	-55 to +150
Storage temperature	T _{STG}	°C	-55 to +150

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■ Electrical Characteristics (T_a=25°C Unless otherwise specified)

Parameter	Symbol	Unit	Conditions	Min	Typ	Max
Reverse voltage	V _R	V	I _R =150uA	350		
Forward voltage	V _{F1}	V	I _F =20mA			0.87
	V _{F2}	V	I _F =100mA			1
	V _{F3}	V	I _F =200mA			1.25
Reverse leakage current	I _R	nA	V _R =240V			100
Junction capacitance	C _j	pF	V _R =0V, f=1MHz			5
Reverse recovery time	T _{rr}	ns	I _F =30mA, I _R =30mA R _L =100Ω, I _{rr} =3mA			50

■ Thermal Characteristics

Parameter	Symbol	Unit	Value
Thermal resistance, junction-to-ambient	R _{θJ-A} ⁽¹⁾	°C/W	357
Thermal resistance, junction-to-case	R _{θJ-C} ⁽¹⁾	°C/W	286

Note:

(1) Device mounted on PCB, single-sided copper, with standard footprint

MMBD3004S

■ Characteristics

Fig 1: P_D - T_a Curve

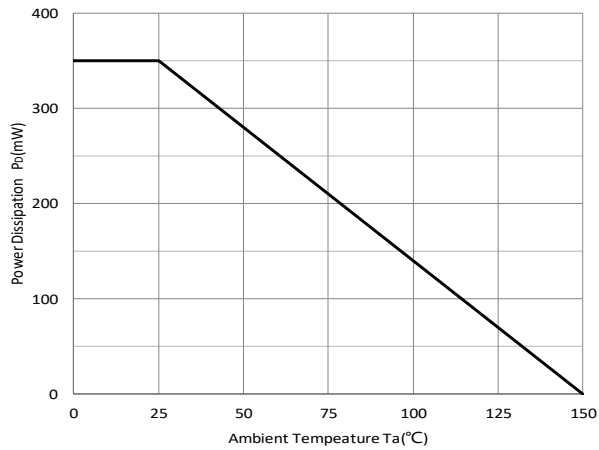


Fig 2: Capacitance Capability

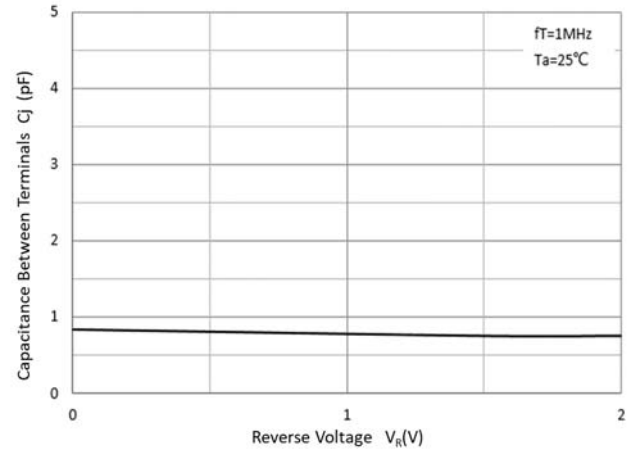


Fig 3: Typical Forward Characteristics

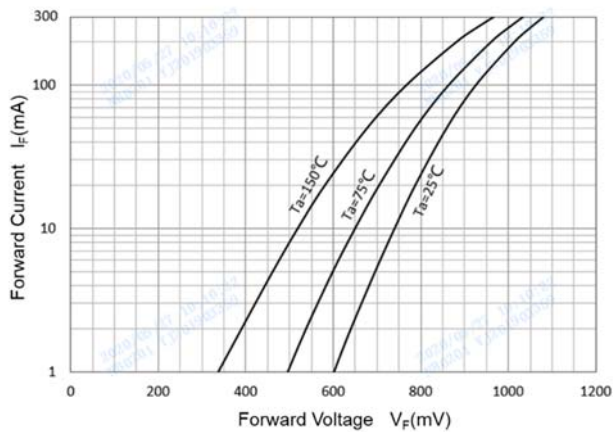
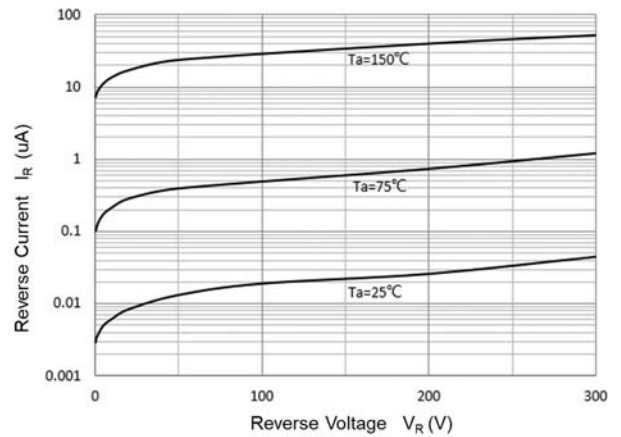


Fig 4: Typical Reverse Characteristics

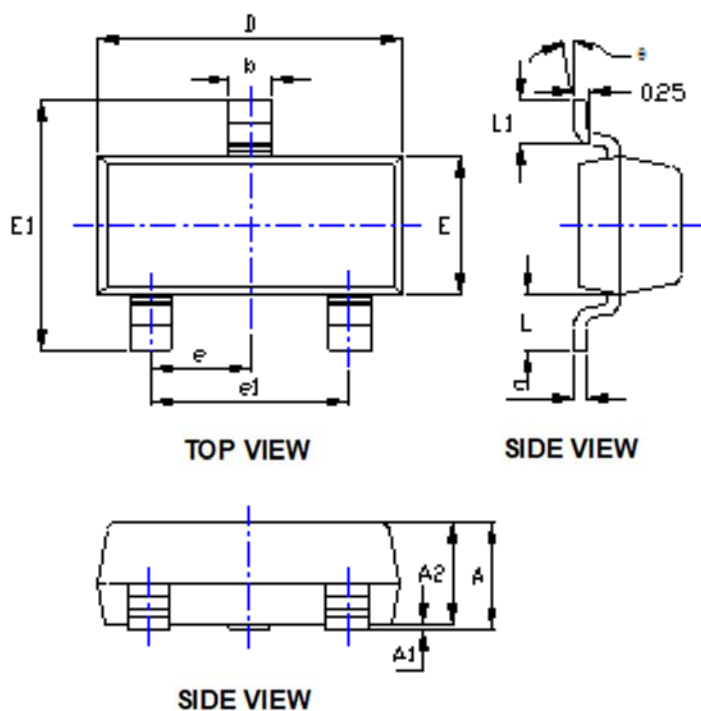


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■ Ordering Information

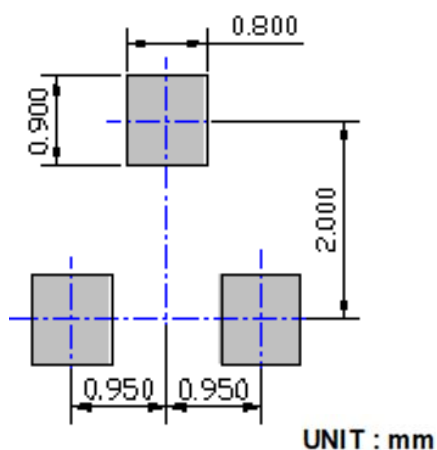
Preferred P/N	Packing code	Unit weight(g)	Minimum package(pcs)	Inner box quantity(pcs)	Outer carton quantity (pcs)	Delivery mode
MMBD3004S	F2	Approximate 0.008	3000	30000	120000	7" reel
MMBD3004S	F4	Approximate 0.008	10000	/	210000	13" reel

■ Outline Dimensions



SYMBOL	DIMENSIONS			
	INCHES		Millimeter	
	MIN.	MAX.	MIN.	MAX.
A	0.035	0.045	0.900	1.150
A1	0.000	0.004	0.000	0.100
A2	0.035	0.041	0.900	1.050
b	0.012	0.020	0.300	0.500
c	0.004	0.008	0.100	0.200
D	0.110	0.118	2.800	3.000
E	0.047	0.055	1.200	1.400
E1	0.089	0.100	2.250	2.550
e	0.037TYP		0.950TYP	
e1	0.071	0.079	1.800	2.000
L	0.022REF		0.550REF	
L1	0.012	0.020	0.300	0.500
θ	0°	8°	0°	8°

■ Suggested Pad Layout



MMBD3004S

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